



80A 2601-CIP.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#12  
5/11/99  
Pgen

In re Application of:

KENICHI NAKAMURA )

Serial No. 08/884,778 )

Filed: June 30, 1997 )

For: BIODEGRADABLE MOLDING )  
MATERIAL )

Group Art Unit: 1755

Examiner: M. Marcheschi

LETTER

Hon. Commissioner of Patents and Trademarks  
Washington, D.C. 20231

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GROUP 1700

Dear Sir:

In connection with the above-identified application, enclosed herewith please find two  
(2) certified copies of the corresponding Japanese Patent Applications No. 8-78400 filed on March  
5, 1996 and No. 9-152828 filed on May 26, 1997, upon which Convention Priority is claimed.

Respectfully submitted,

KODA AND ANDROLIA

By: 

William L. Androlia

Reg. No. 27,177

10100 Santa Monica Boulevard  
Suite 2340  
Los Angeles, CA 90067  
(310) 277-1391

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